

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re application of: Rosengaus and Lange

Attorney Docket No.: KLA1P001C1

Application No.: To Be Assigned

Examiner: To Be Assigned

Filed: HERewith

Group: To Be Assigned

Title: System and Method for Inspecting  
Semiconductor Wafers**CERTIFICATE OF MAILING**

I hereby certify that this paper and the documents and/or fees referred to as attached therein are being deposited with the United States Postal Service on December 30, 1999 in an envelope as "Express Mail Post Office to Addressee" service under 37 CFR §1.10, Mailing Label Number **EL065189610US**, addressed to the Assistant Commissioner for Patents, Washington, DC 20231.

Signed:

Dionna Holmes  
Dionna Holmes**PRELIMINARY AMENDMENT**

Assistant Commissioner for Patents  
Box Patent Application  
Washington, D.C. 20231

Dear Sir:

Prior to an examination on the merits, please enter the following amendments:

**In the Specification:**

Page 1, line 6, please insert:

Q' -- This is a continuation application of Application No. 09/070,437, filed April 30, 1998,  
the disclosure of which is incorporated herein by reference.--

**In the Claims:**

Please cancel claims 23-42.

Please amend claim 1 as follows:

- Q<sup>2</sup>  
Sub B
1. (Amended) An integrated circuit manufacturing system comprising:
    - (a) a plurality of interrelated integrated circuit manufacturing tools capable of operating in parallel on a plurality of semiconductor wafers;